

ABSTRACT

**SEMICONDUCTOR MULTI-PACKAGE MODULE
HAVING PACKAGE STACKED OVER BALL GRID ARRAY PACKAGE
AND HAVING WIRE BOND INTERCONNECT BETWEEN STACKED PACKAGES**

A semiconductor multi-package module having a second package stacked over a lower ball grid array first package, each package including a die attached to a substrate, in which the first and second package substrates are interconnected by wire bonding. Also, a method for making a semiconductor multi-package module, by providing a ball grid array first package including a substrate and a die, affixing a second package including a substrate and a die onto an upper surface of the lower package, and forming z-interconnects between the first and lower substrates.